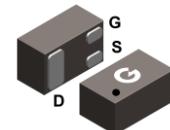
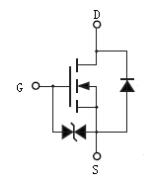


## Features

- N-Channel switch with low  $R_{DS(on)}$
- Operated at low logic level gate drive

**HF**

**DFN1006-3**

## Mechanical Data

- Case: DFN1006-3
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL1014L	DFN1006-3	10000 pcs / Tape & Reel	KM

## Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	30	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	0.6	A
Pulsed Drain Current *1	$I_{DM}$	1.8	A

## Thermal Characteristics

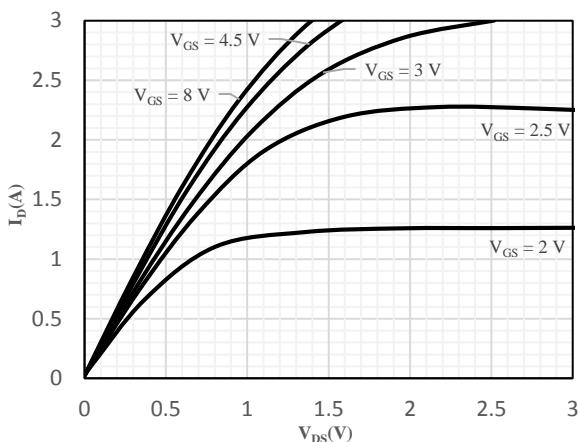
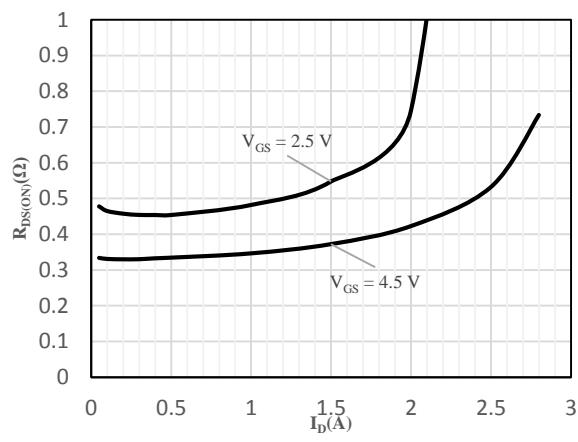
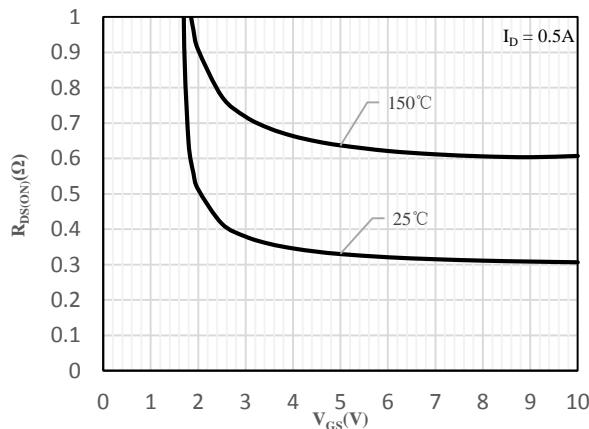
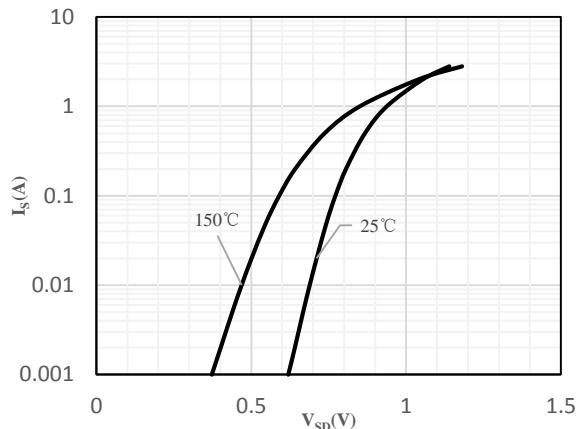
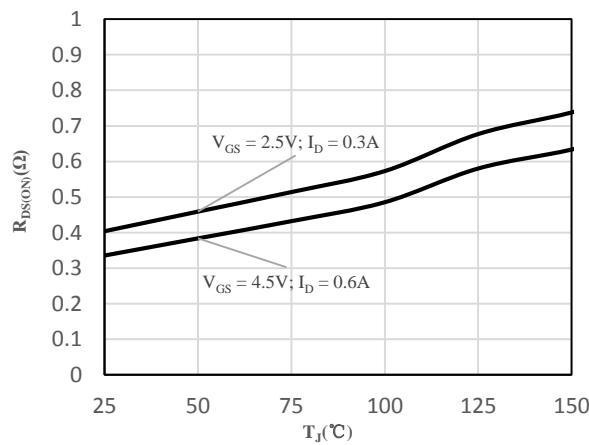
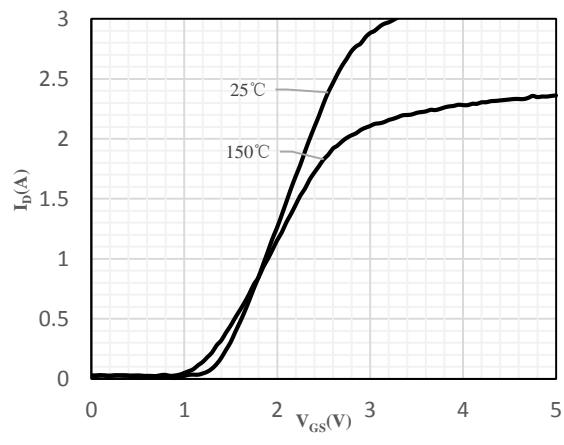
Parameter	Symbol	Value	Unit
Power Dissipation *2	$P_D$	0.15	W
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	833	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

**Electrical Characteristics** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}$	30	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 10V, V_{DS} = 0V$	-	-	$\pm 3$	$\mu\text{A}$
<b>On Characteristics</b>						
$R_{DS(ON)}$	Static Drain-Source On-resistance * <sup>3</sup>	$V_{GS} = 4.5V, I_D = 0.6A$	-	335	420	$\text{m}\Omega$
		$V_{GS} = 2.5V, I_D = 0.3A$	-	404	540	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.95	1.5	V
<b>Dynamic Characteristics</b>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 10V$ $f = 1.0\text{MHz}$	-	73	-	pF
$C_{OSS}$	Output Capacitance		-	29	-	
$C_{RSS}$	Reverse Transfer Capacitance		-	16	-	
$Q_G$	Total Gate-Charge	$V_{DS} = 15V$ $V_{GS} = 4.5V$ $I_D = 0.8A$	-	2.23	-	nC
$Q_{GS}$	Gate to Source Charge		-	0.63	-	
$Q_{GD}$	Gate to Drain (Miller) Charge		-	0.38	-	
<b>Switching Characteristics</b> * <sup>4</sup>						
$t_{d(ON)}$	Turn-on Delay Time	$V_{DS} = 15V$ $V_{GS} = 4.5V$ $R_G = 51\Omega$ $I_D = 0.7A$	-	5	-	ns
$t_r$	Turn-on Rise Time		-	8.2	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	23	-	
$t_f$	Turn-Off Fall Time		-	41	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage * <sup>3</sup>	$I_{SD} = 0.6A, V_{GS} = 0V$	-	0.9	1.2	V

Notes:

1. Repetitive rating: Pulse width limited by maximum junction temperature
2. Device mounted on FR-4 PCB
3. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 0.5\%$
4. These parameters have no way to verify

**Ratings and Characteristic Curves** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

**Fig 1 Output Characteristics**

**Fig 2 On-Resistance vs. Drain Current and Gate Voltage**

**Fig 3 On-Resistance vs. Gate-Source Voltage**

**Fig 4 Body-Diode Characteristics**

**Fig 5 On-Resistance vs. Junction Temperature**

**Fig 6 Transfer Characteristics**

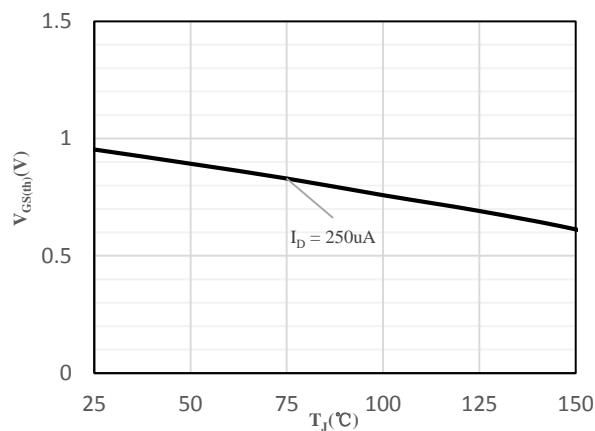


Fig 7 Gate Voltage vs. Junction Temperature

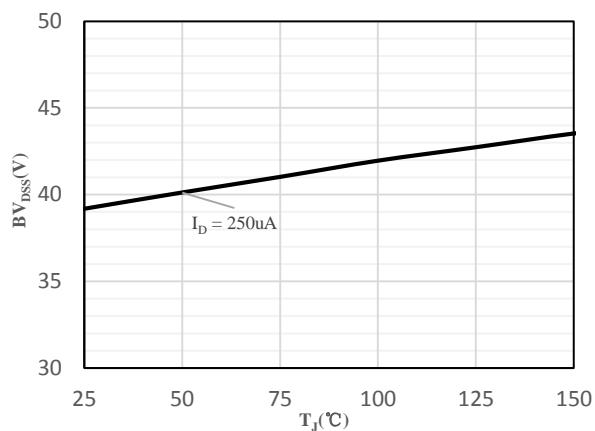


Fig 8 Drain-Source vs. Junction Temperature

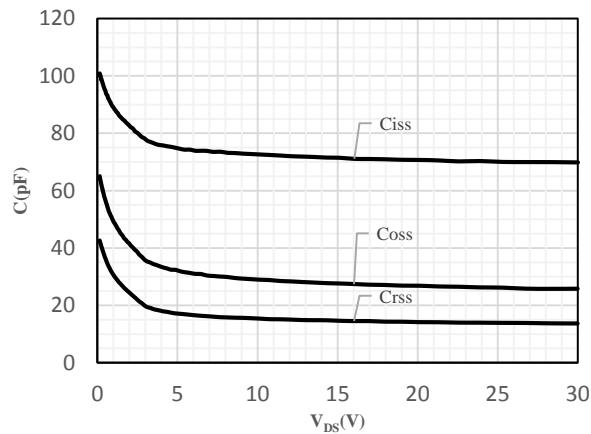


Fig 9 Capacitance Characteristics

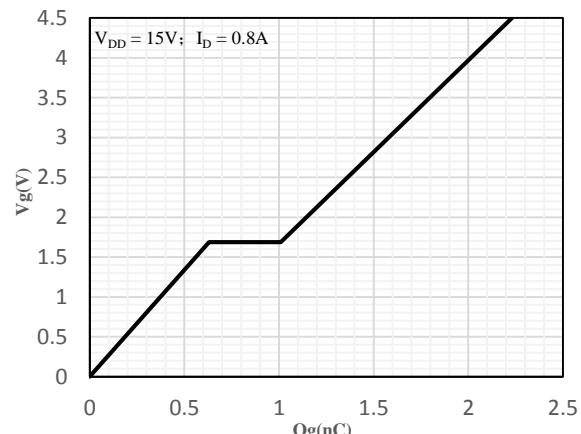
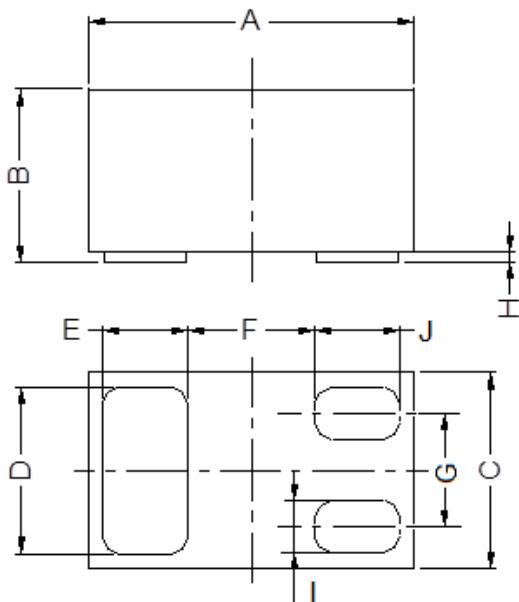


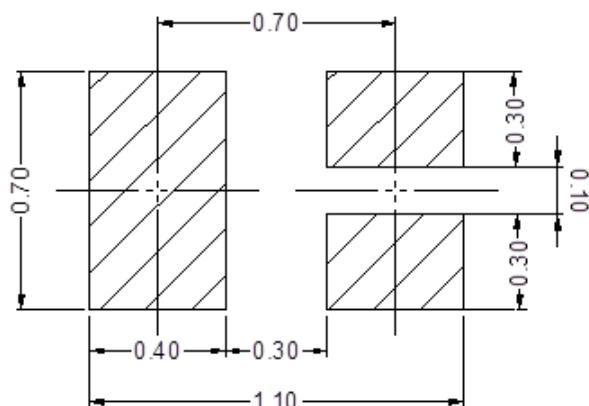
Fig 10 Gate-Charge Characteristics

### Package Outline Dimensions (Unit: mm)



DFN1006-3			
Dimension	Min.	Typ.	Max.
A	0.95	1.00	1.075
B	0.47	0.50	0.53
C	0.55	0.60	0.675
D	0.45	0.50	0.55
E/J	0.20	0.25	0.30
F	-	0.40	-
G	-	0.35	-
H	0	0.03	0.05
I	0.10	0.15	0.20

### Package Outline Dimensions (Unit: mm)

**DFN1006-3**


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